# 1.8V Drive Nch+SBD MOSFET

# **QS5U34**

#### Structure

Silicon N-channel MOSFET Schottky Barrier DIODE

#### ● Features

- 1) The QS5U34 combines Nch MOSFET with a Schottky barrier diode in a single TSMT5 package.
- 2) Low on-state resistance with fast switching.
- 3) Low voltage drive (1.8V).
- 4) The Independently connected Schottky barrier diode has low forward voltage.

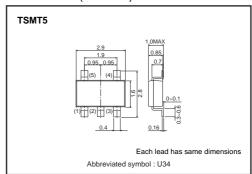
# Applications

Load switch, DC / DC conversion

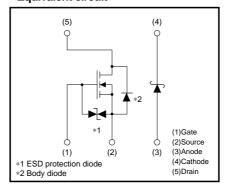
# Packaging specifications

	Package	Taping	
Туре	Code	TR	
	Quantity (pcs)	3000	
QS5U34		0	

# ●Dimensions (Unit: mm)



### ●Equivalent circuit





# ● Absolute maximum ratings (Ta=25°C)

#### <MOSFET>

Parameter	Symbol	Limits	Unit				
Drain-source voltage	V <sub>DSS</sub>	20	V				
Gate-source voltage	V <sub>GSS</sub>	10	V				
Drain current	Continuous	ΙD	±1.5	А			
Drain current	Pulsed	I <sub>DP</sub> *1	±3.0	Α			
Source current	Continuous	Is	0.6	А			
(Body diode)	Pulsed	I <sub>SP</sub> *1	2.4	А			
Channel temperature	Tch	150	°C				
Power dissipation	P <sub>D</sub> *3	0.9	W/ELEMENT				
<di></di>							
Repetitive peak reverse volta	V <sub>RM</sub>	30	V				
Reverse voltage	$V_R$	20	V				
Forward current	l <sub>F</sub>	0.5	А				
Forward current surge peak	I <sub>FSM</sub> *2	2.0	А				
Junction temperature	Tj	150	°C				
Power dissipation	P <sub>D</sub> *3	0.7	W/ELEMENT				
<mosfet and="" di=""></mosfet>							
Total power dissipation	P <sub>D</sub> *3	1.25	W / TOTAL				
Range of Storage temperatu	Tstg	-55 to +150	°C				

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 60Hz•1cyc. \*3 Mounted on a ceramic board

# ●Electrical characteristics (Ta=25°C)

# <MOSFET>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	-	_	10	μΑ	V <sub>GS</sub> =10V / V <sub>DS</sub> =0V	
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	20	_	_	V	I <sub>D</sub> =1mA, / V <sub>GS</sub> =0V	
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	V <sub>DS</sub> =20V / V <sub>GS</sub> =0V	
Gate threshold voltage	VGS (th)	0.3	_	1.3	V	Vps=10V / Ip=1mA	
Out to the total out of the		_	130	180	$m\Omega$	I <sub>D</sub> =1.5A, V <sub>GS</sub> =4.5V	
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	170	240	mΩ	I <sub>D</sub> =1.5A, V <sub>GS</sub> =2.5V	
10313tai 10 <del>0</del>		_	220	310	mΩ	I <sub>D</sub> =0.8A, V <sub>GS</sub> =1.8V	
Forward transfer admittance	Y <sub>fs</sub>   *	1.6	_	_	S	Vps=10V, Ip=1.5A	
Input capacitance	Ciss	-	110	_	pF	V <sub>DS</sub> =10V	
Output capacitance	Coss	-	18	_	pF	V <sub>GS</sub> =0V	
Reverse transfer capacitance	Crss	_	15	-	pF	f=1MHz	
Turn-on delay time	<b>t</b> d (on) *	-	5	_	ns	Ib=1.0A	
Rise time	tr *	-	5	_	ns	VDD≒10V	
Turn-off delay time	t <sub>d (off)</sub> *	_	20	_	ns	V <sub>GS</sub> =4.5V R∟=10Ω	
Fall time	t <sub>f</sub> *	-	3	-	ns	R <sub>G</sub> =10Ω	
Total gate charge	Qg *	_	1.8	2.5	nC	V <sub>DD</sub> ≒10V	
Gate-source charge	Q <sub>gs</sub> *	_	0.3	-	nC	V <sub>GS</sub> =4.5V	
Gate-drain charge	Q <sub>gd</sub> *	_	0.3	_	nC	I <sub>D</sub> =1.5A	

### <MOSFET>Body diode (source-drain)

Forward voltage	Vsp	_	_	1.2	V	I <sub>S</sub> =0.6A / V <sub>GS</sub> =0V

# <Di>

Forward voltage	VF	_	_	0.36	V	I <sub>F</sub> =0.1A
		_	_	0.47	V	I <sub>F</sub> =0.5A
Reverse current	lR	_	_	100	μА	V <sub>R</sub> =20V



#### •Electrical characteristic curves

#### <MOSFET>

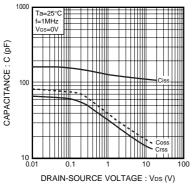


Fig.1 Typical Capacitance vs. Drain-Source Voltage

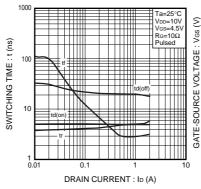


Fig.2 Switching Characteristics

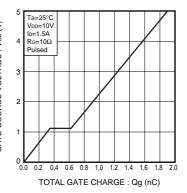


Fig.3 Dynamic Input Characteristics

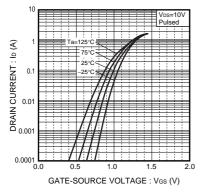


Fig.4 Typical Transfer Characteristics

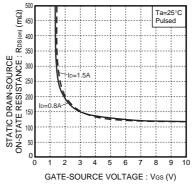


Fig.5 Static Drain-Source On-State Resistance vs. Gate-source Voltage

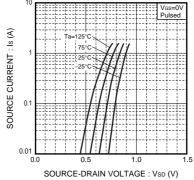


Fig.6 Source Current vs. Source-Drain Voltage

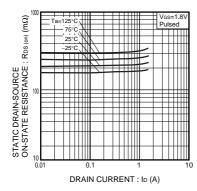


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current ( I )

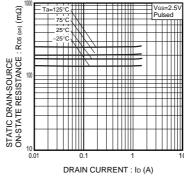


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current ( II )

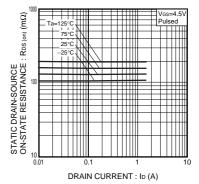
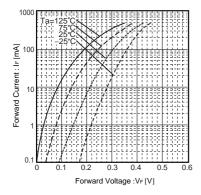


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current ( III )





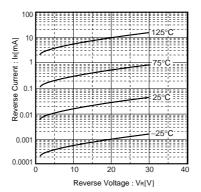


Fig.10 Forward Temperature Characteristics

Fig.11 Reverse Temperature Characteristics



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